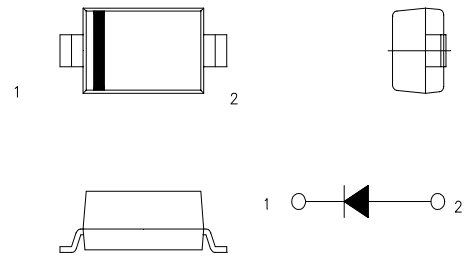


SBD Type : EP05Q03L

FEATURES

- * EDEC SOD-123 Package
- * Very Low profile 1.1mm Max
- * Extremely Low Forward Voltage Drop
- * Low Power Loss,High Efficiency
- * High Surge Capability
- * Low Thermal Resistance
- * Packaged in 8mm Tape and Reel

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.011g

| Rating | Symbol | EP05Q03L | | Unit | |
|-------------------------------------|--------------|-------------|--|--|---|
| Repetitive Peak Reverse Voltage | V_{RRM} | 30 | | V | |
| Average Rectified Output Current | I_O | 0.49 | $T_a=25^{\circ}\text{C}$ * 1 | 50Hz Half Sine Wave, Resistive Load | A |
| | | 0.50 | $T_l=106^{\circ}\text{C}$ | | |
| RMS Forward Current | $I_{F(RMS)}$ | 0.785 | | A | |
| Surge Forward Current | I_{FSM} | 8 | 50Hz Half Sine Wave,1cycle Non-repetitive | A | |
| Operating JunctionTemperature Range | T_{jw} | -40 to +150 | | $^{\circ}\text{C}$ | |
| Storage Temperature Range | T_{stg} | -40 to +150 | | $^{\circ}\text{C}$ | |

Electrical • Thermal Characteristics

| Characteristics | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|----------------------|---------------|--|------|------|------|-----------------------------|
| Peak Reverse Current | I_{RM} | $T_j= 25^{\circ}\text{C}$, $V_{RM}= V_{RRM}$ | - | - | 200 | μA |
| Peak Forward Voltage | V_{FM} | $T_j= 25^{\circ}\text{C}$, $I_{FM}=0.5\text{A}$ | - | - | 0.45 | V |
| Thermal Resistance | $R_{th(j-a)}$ | Junction to Ambient * | - | - | 300 | $^{\circ}\text{C}/\text{W}$ |
| | $R_{th(j-l)}$ | Junction to Lead | - | - | 70 | |

*1: Glass Epoxy Substrate Mounted (Soldering Lands=1x1mm,Both Sides)
(T_l : Lead Temperature)

EP05Q03L OUTLINE DRAWING (Dimensions in mm)

